

Title (en)

METHOD FOR ELECTROCHEMICALLY METALLISING AN INSULATING SUBSTRATE

Title (de)

VERFAHREN ZUR ELEKTROCHEMISCHEN METALLISIERUNG EINES ISOLIERENDEN SUBSTRATS

Title (fr)

PROCEDE DE METALLISATION D'UN SUBSTRAT ISOLANT PAR VOIE ELECTROCHIMIQUE

Publication

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Application

EP 00966282 A 20001004

Priority

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Abstract (en)

[origin: US6764586B1] Provided is a process for metallizing an insulating substrate by depositing a uniform thin film of a metal on the insulating substrate. The process comprises placing the insulating substrate in an electrochemical cell which contains as the electrolyte a solution of a salt of the metal in a solvent, and which comprises an anode of the metal and a cathode in direct contact with the insulating substrate. A conducting film, which will constitute the cathode, is initially applied to one end of the substrate. The substrate is placed in the electrochemical cell in such a way that the surface to be metallized is vertical and the cathode is located in the upper part. A current is imposed on the electrochemical cell with an intensity such that it creates a current density of between 1 and 50 mA/cm² in the horizontal section of the electrochemical cell level with the growth front of the film which is deposited.

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